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ATTY. DOCKET NO.
EN9-97-075USS

SERIAL NO.

Francis J. Downes et al.

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5203**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
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	5,121,190	6/1992	Hsiao et al.			
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	10-209347	8/1998	Japan				
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	6-112271	4/1994	Japan				

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		IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT."
		PROCESS CONSIDERATIONS IN THE FABRICATION OF TEFLON PRINTED CIRCUIT BOARDS, Light et al., 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94.

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		HIGH PERFORMANCE CARRIER TECHNOLOGY: MATERIALS AND FABRICATION, Light et al., 1993 International Electronics Packaging Conference, San Diego, CA Volume One.
		HIGH PERFORMANCE CARRIER TECHNOLOGY, Heck et al., 1993 International Electronics Packaging Conference, San Diego, CA, Volume One.

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